



FLH Ref. No.: 450100-4443

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.			
1. Name of conveying party(ies)	2. Name and ac	ddress of receiving party(ies)	
Keiji KANOTA, Shunji OKADA, Nobuko FUJ		SONY CORPORATION 7-35 Kitashinagawa 6-chome Shinagawa-Ku, Fokyo 100-31, Japan	
Additional name(s) of conveying party(ies) a Yes _X_ No		e(s) & address(es) attached?Yes _x_ No	
3. Nature of conveyance:			
X Assignment Security Agreement Merger Change of Name Other			
Execution Date(s): July 14, July 14, and July 25	, 1998.		
4. Application number(s) or patent number(s):			
If this document is being filed together with a new application, the execution date of the application is:			
A. Patent Application No.(s) 09/079,934 filed May 15, 1998			
Additional numbers attached? <u>X</u> No			
Name and address of party to whom corresponde concerning document should be mailed:		er of applications and volved 1_	
Name: WILLIAM S. FROMMER	7. Total fee ((37 CFR 3.41) \$ 40.00	
Internal Address: FROMMER LAWRENCE & HAUG LLP	<u>x</u>	Enclosed Authorized to be charged to	
Street Address: 745 FIFTH AVENUE		deposit account 50-0320	
City: <u>NEW YORK</u> State: <u>N.Y.</u> Zip: <u>101</u>	51 8. Deposit acc (Attach duplica account)	count number: ite copy of this page if paying by deposit	
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9. Statement and signature. To the best of my knowledge and belief, the f copy of the original document. **TOO WILLIAM S. FROMMER** Name of Person Signing	oregoing information is true and the second of the second	August 13, 1998 Date Total number of pages including cover sheet, attachments, and document: 2	
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ASSIGNMENT

FLH File No. 450100-4443

WHEREAS, 1, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

DATA RECORDING APPARATUS AND METHOD, DATA REPRODUCING APPARATUS AND METHOD, DATA RECORDING/REPRODUCING APPARATUS AND METHOD, AND TRANSMISSION MEDIUM

for which application for Letters Patent of the United States of America was executed by me or the date indicated next to my name and address:

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$^.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/079,934, Filing Date: May 15, 1998.

This assignment executed on the dates indicated below.

Keiji KANOTA	July 14, 1988	
Name of first or sole inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of first or sole inventor Keiji Kanola	July 14, 1998 Date of this assignment	
Signature of first or sole inventor ℓ	Date of this assignment	
Shunji OKADA	July 14, 1998	
Name of second inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of second inventor Shunii Ckada.	July 14, 1998	
Signature of second inventor	Date of this assignment	
Nobuko FUJII	July 25, 1918 Execution date of U.S. Patent Application	
Name of third inventor	Execution date of U.S. Patent Application	
Miyagi. Japan		
Residence of third inventor Nobuko Juju	July 25, 1990	
Signature of third inventor	Date of this assignment	

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